



#### N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

Device	BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C (Note 10)
		11.1m $\Omega$ @ V <sub>GS</sub> = 10V	30A
Q1 & Q2	30V	13.8m $\Omega$ @ V <sub>GS</sub> = 4.5V	28A
		$22.0 \text{m}\Omega$ @ $V_{GS} = 3.8V$	22A

### **Features and Benefits**

- Low Gate Threshold Voltage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Description**

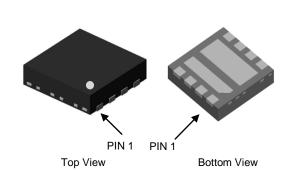
This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## **Applications**

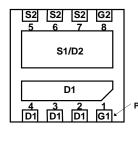
- General Purpose Interfacing Switch
- Power Management Functions

### **Mechanical Data**

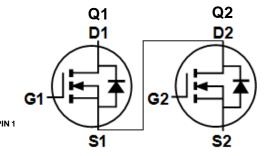
- Case: V-DFN3030-8 (Type K)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208
- Weight: 0.02 grams (Approximate)



## V-DFN3030-8 (Type K)







**Equivalent Circuit** 

### **Ordering Information** (Note 4)

Part Number	Case	Tape Width	Tape Pitch	Packaging
DMT3009LDT-7	V-DFN3030-8 (Type K)	8mm	4mm	3,000/Tape & Reel
DMT3009LDT-7A	V-DFN3030-8 (Type K)	12mm	8mm	1,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See http://www.diodes.com/quality/lead\_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**

#### V-DFN3030-8 (Type K)



T30= Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



# 

Characteristic	Symbol	Q1&Q2	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	30	V		
Gate-Source Voltage	V <sub>GSS</sub>	+20, -16	V		
Continuous Drain Current (Note C) V 40V	Steady State (Note 10)	$T_C = +25$ °C $T_C = +70$ °C	I <sub>D</sub>	30 25	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	14 11	Α
Maximum Body Diode Forward Current (Note 6)	Is	2.1	Α		
Pulsed Drain Current (100µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	80	Α		
Pulsed Body Diode Forward Current (370µs Pulse, Duty C	I <sub>SM</sub>	80	Α		
Avalanche Current (Note 7) L = 0.1mH	I <sub>AS</sub>	19.3	Α		
Avalanche Energy (Note 7) L = 0.1mH	E <sub>AS</sub>	18.6	mJ		

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	6	1.2	W
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	$P_{D}$	0.8	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	107	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	63	
Total Power Dissination (Note 6)	$T_A = +25$ °C	D-	2.0	W
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P <sub>D</sub>	1.2	
Thormal Bosistanos, Junatian to Ambient (Note 6)	Steady State	D	64	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	39	
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	7.6	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
   Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
- 7. UIS in production with L = 0.1mH, starting  $T_A = +25$ °C.



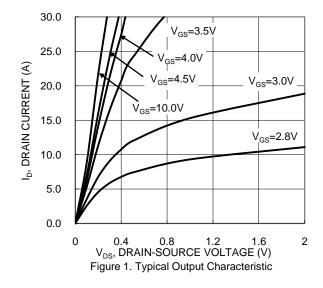
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

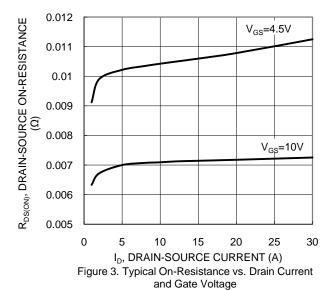
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		1	1	μΑ	$V_{DS} = 24V$ , $V_{GS} = 0V$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +150°C (Note 9)	I <sub>DSS</sub>		ı	100	μΑ	$V_{DS} = 24V$ , $V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>		_	±100	nA	$V_{GS} = 20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	1	3	٧	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			7.2	11.1		$V_{GS} = 10V, I_D = 14.4A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		10.5	13.8	mΩ	$V_{GS} = 4.5V, I_D = 7A$	
			13	22.0		$V_{GS} = 3.8V, I_D = 5A$	
Diode Forward Voltage	$V_{SD}$			1.2	٧	$V_{GS} = 0V, I_{S} = 10A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	748	1,500		V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss		447	895	pF		
Reverse Transfer Capacitance	Crss	_	43	90			
Gate Resistance	$R_{g}$		1.0	2.0	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_{g}$	_	13.8	20		V <sub>DS</sub> = 15V, I <sub>D</sub> = 14.4A	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$		6.4	9	nC		
Gate-Source Charge	$Q_gs$		2.2	5	110	VDS = 13V, ID = 14.4A	
Gate-Drain Charge	$Q_{gd}$		2.2	5			
Turn-On Delay Time	t <sub>D(ON)</sub>		3.5	7		$V_{GS} = 10V, V_{DD} = 15V, R_g = 1\Omega,$ $I_D = 10A$	
Turn-On Rise Time	t <sub>R</sub>		5.0	10	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>		8.6	17	115		
Turn-Off Fall Time	t <sub>F</sub>		1.4	3			
Body Diode Reverse Recovery Time	t <sub>RR</sub>		18	33	ns	$I_F = 10A$ , $di/dt = 100A/\mu s$	
Body Diode Reverse Recovery Charge	$Q_{RR}$		7.7	15	nC	$I_F = 10A$ , di/dt = $100A/\mu s$	

Notes:

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.
 Package limited.







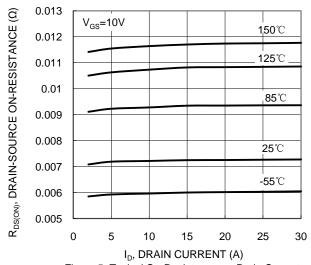
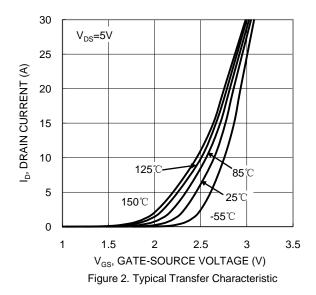
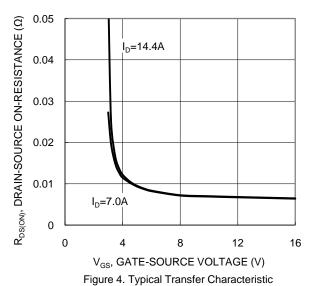


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





ш 1.8 С

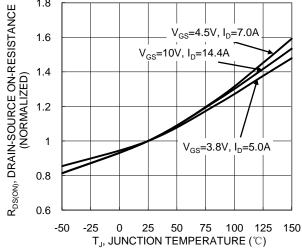


Figure 6. On-Resistance Variation with Junction Temperature



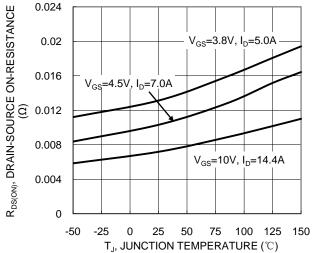


Figure 7. On-Resistance Variation with Junction Temperature

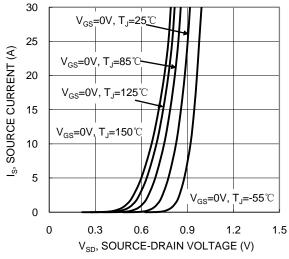
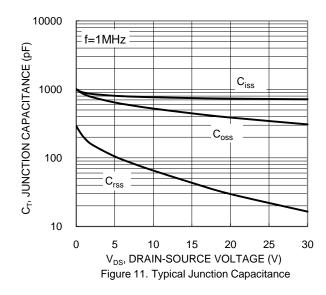


Figure 9. Diode Forward Voltage vs. Current



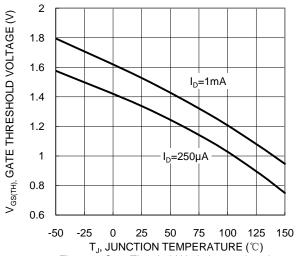


Figure 8. Gate Threshold Variation vs. Junction Temperature

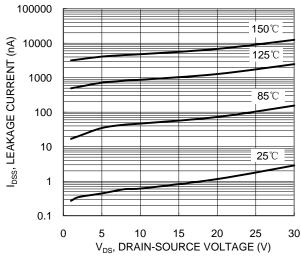
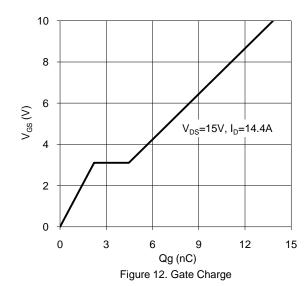
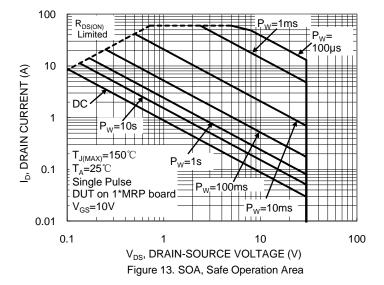
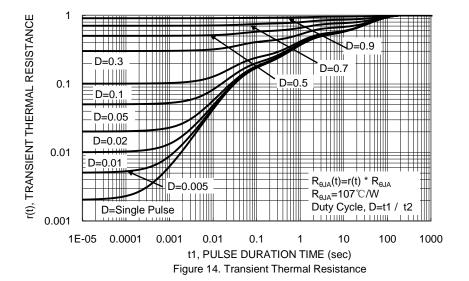


Figure 10. Typical Drain-Source Leakage Current vs. Voltage







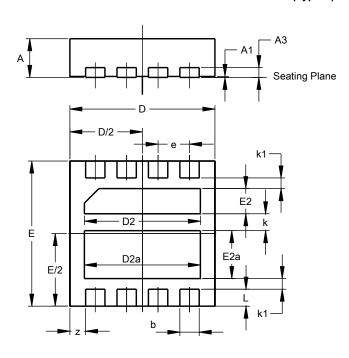




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### V-DFN3030-8 (Type K)

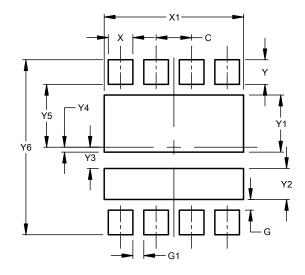


V-DFN3030-8						
	(Type K)					
Dim	Min	Max	Тур			
Α	0.77	0.85	0.80			
A1	0.00	0.05	0.02			
A3	0.20BSC					
b	0.35	0.45	0.40			
D	2.95	3.050	3.00			
D2	2.30	2.50	2.40			
D2a	2.30	2.50	2.40			
Е	2.95	3.050	3.00			
E2	0.42	0.62	0.52			
E2a	0.89	1.09	0.99			
е	0.65BSC					
k	-	-	0.35			
k1	-	-	0.22			
L	0.30	0.40	0.35			
Z	0.325BSC					
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### V-DFN3030-8 (Type K)



Dimensions	Value (in mm)		
С	0.650		
G	0.195		
G1	0.200		
X	0.450		
X1	2.550		
Y	0.450		
Y1	1.044		
Y2	0.566		
Y3	0.389		
Y4	0.089		
Y5	1.150		
Y6	3.200		



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